

Experiment-1

Boost converter Design document

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1. SYSTEM UNDER CONSIDERATION:

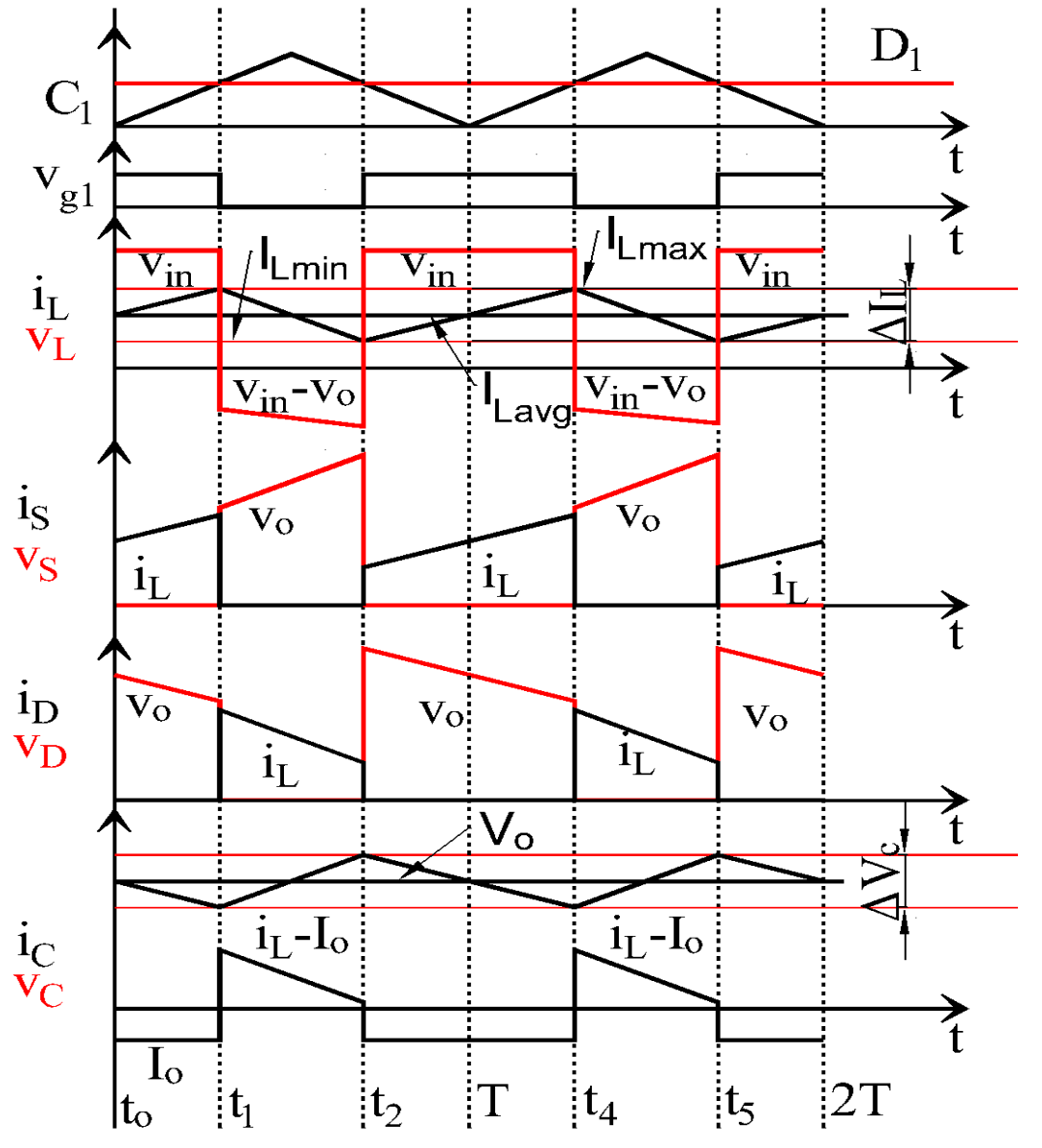
Let us consider a system:

$V_{in} = 20$ to $28.8V$ (2 Lead acid battery of $12V$ in series), Rated $V_{in} = 24V$

$V_{out} = 48V$ (DC bus), Rated Power = 200 W, and switching frequency (f_s) = 50 kHz.

Design the system for the worst-case condition considering the above-mentioned criteria such that the inductor current ripple (p-p) *i.e.* $\Delta I_{L(p-p)}$ and capacitor voltage ripple (p-p) *i.e.* $\Delta V_{C(p-p)}$ should not exceed 30% and 2% respectively for full load condition and find out upto what load the converter will operate in CCM. Consider the non-idealities like R_{dsON} , R_L , V_D and ESR of Capacitance etc.

2. KEY BOOST CONVERTER WAVEFORMS:



3. SELECTION OF MOSFET:

Blocking voltage of mosfet and diode (V_{dd}) = load voltage (V_o) = 48V

Safety factor to be considered = 2 (due to voltage spikes due to parasitic inductance and reverse recovery of diode)

Voltage rating of MOSFET (V_{br}) = 100V

Also Maximum current through switch = inductor current = $200W/20V = 10A$.

• CONDUCTION LOSS:

Without considering inductor ripple.

RMS switch current (I_{srms}) = $I_{in}\sqrt{D} = 7.635A$ ($10\sqrt{0.583}$)

IRF540NLPbF is the mosfet chosen for the boost converter.

Blocking voltage of mosfet = 100V

Maximum Drain current at 125°C = 17.5A (From fig 9).

R_{ds} of MOSFET at 125°C = $2.25 \times 44m\Omega = 99m\Omega$

Maximum conduction Loss in the switch = $I_{srms}^2 R_{ds} = 5.77W$

• SWITCHING LOSS:

Since for low power and low voltage system, Power Schottky diode is selected which has negligible reverse recovery loss during its turn-off.

From fig. 5 of **IRF540NLPbF** datasheet

C_{gd} at $V_{dd}(50V)$ $C_{gd1} = 40pF$

C_{gd} at $I_{ds} \times R_{ds}(0.99V)$ $C_{gd2} = 500pF$

Gate Threshold voltage $V_{gth} = 4V$

From fig. 3 of **IRF540NLPbF** datasheet

At 175°C $V_{g1} = 4V$ $i_{d1} = 12A$; $V_{g2} = 6V$ $i_{d2} = 60$

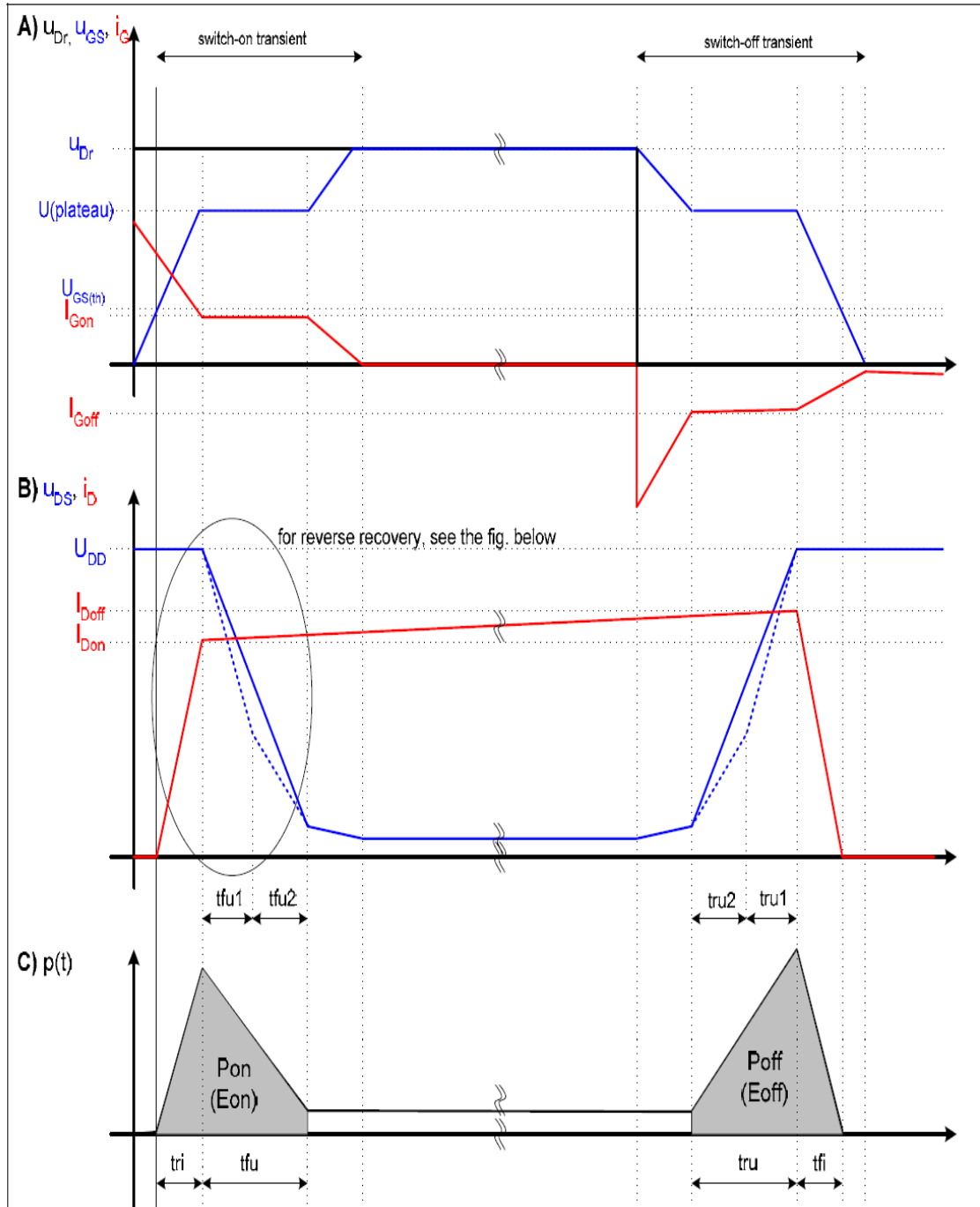
$$V_{th} = \frac{V_{g1}\sqrt{i_{d2}} - V_{g2}\sqrt{i_{d1}}}{\sqrt{i_{d2}} - \sqrt{i_{d1}}} = 2.382V; k = \frac{i_{d1}}{(V_{g1} - V_{th})^2} = 4.584$$

$$V_{GS,miller} = V_{th} + \sqrt{\frac{I_{load}}{k}} = 2.382 + \sqrt{\frac{10}{4.584}} = 3.859$$

$$V_{adj} = (125 - 175) * \left(-0.007 \frac{^{\circ}C}{V}\right) = +0.35V; \text{(From class notes)}$$

$$V_{plateau} = 3.859 + 0.35 = 4.21V$$

Gate drive voltage (V_{dr}) = 15V; Gate resistance $R_g = 10\Omega$



Current rise time of the switch (t_r) = 35ns (from datasheet).

$$\text{Voltage fall time 1 } t_{fu1} = (V_{dd} - I_{ds} * R_{ds}) * R_g * \frac{C_{gd1}}{V_{dr} - V_{plateau}} = 1.74ns$$

$$\text{Voltage fall time 1 } t_{fu2} = (V_{dd} - I_{ds} * R_{ds}) * R_g * \frac{C_{gd2}}{V_{dr} - V_{plateau}} = 21.78ns$$

$$\text{Average voltage fall time } t_{fu} = \frac{t_{fu1} + t_{fu2}}{2} = 11.76ns$$

Current fall time of the switch (t_f) = 35ns (from datasheet)

$$\text{Voltage rise time 1 } t_{ru1} = (V_{dd} - I_{ds} * R_{ds}) * R_g * \frac{C_{gd1}}{V_{plateau}} = 0.447ns$$

$$\text{Voltage rise time 1 } t_{ru2} = (V_{dd} - I_{ds} * R_{ds}) * R_g * \frac{C_{gd2}}{V_{plateau}} = 5.583ns$$

$$\text{Average voltage rise time } t_{ru} = \frac{t_{ru1} + t_{ru2}}{2} = 3.02ns$$

Power Schottky diode is selected which has negligible reverse recovery loss during its turn-off.

$$\begin{aligned} \text{Switching loss in the switch} &= V_{ofs}((i_{son} * \frac{t_r + t_{fu}}{2}) + (\frac{t_{ru} + t_f}{2} * i_{soff})) \\ &= \frac{1}{2} 48 * 50000 * 10((2 * 35) + 11.76 + 3.02) * 10^{-9} = 1.02W \end{aligned}$$

$$\text{Total Loss of the switch } (P_g) = 5.77W + 1.02W = 6.79W.$$

• MOSFET HEAT SINK DESIGN:

Transient Thermal Impedance Junction-to-Case at 50Khz 0.5 duty cycle (Z_{thc})= 0.7°C/W (From fig 11).

$$\text{Junction Temperature rise with respect to case} = P_g * Z_{thc} = 6.79 * 0.7 = 4.75^\circ \text{ rise.}$$

Let maximum junction temperature T_j be 125°C.

$$\text{Then, maximum case temperature } T_c = 125 - 4.75 = 120.25^\circ\text{C}$$

Let the ambient temperature be 40°C;

$$\text{Maximum heat sink thermal Impedance (Case to ambient) } (Z_a) = \frac{T_c - T_a}{P_g} = \frac{120.25 - 40}{P_g} = 11.81^\circ \frac{C}{W}$$

Selected heat sink thermal Impedance (Case to ambient)= 8°C/W (1.10" Wide x 12" BGA Heatsink Extrusion 16240 xx8052-65)

$$\text{Case Temperature rise with respect to ambient with selected heatsink} = P_g * Z_a = 54.32^\circ \text{ rise}$$

$$\text{Junction Temperature } (T_j) = 40^\circ + 54.32^\circ + 4.75^\circ\text{C} = 99.07^\circ\text{C}.$$

Here junction temperature is well within the operating temperature range of the MOSFET.

4. SELECTION OF DIODE:

Schottky diode STPS20S100C is the diode chosen for this boost converter.

$$\text{Voltage rating of diode } (V_{br}) = 100V$$

$$\text{RMS diode current } (I_{drms}) = I_{in}\sqrt{(1 - D)} = 6.458A (10\sqrt{0.417}) < 30A \text{ (rating)}$$

$$\text{Average diode current } (I_{dav}) = I_{in}(1 - D) = 4.17A < 20A \text{ (rating)}$$

• CONDUCTION LOSS:

$$\text{Forward Voltage of the diode at 10A at 125°C } (V_f) = 0.71V.$$

$$\text{Conduction Loss of the diode} = V_f * i_d * (1 - D) = 0.71 * 10 * 0.417 = 2.96W.$$

• REVERSE LEAKAGE LOSS:

Since **Schottky** diode is used, the reverse leakage losses are more significant than switching losses.

Reverse leakage current (I_r) at 50V blocking = 0.3mA @ $T_j = 125^\circ\text{C}$. (From fig 6)

$$\text{Reverse Leakage Loss of the diode} = V_o * I_r * D = 48 * 0.3 * 10^{-3} * 0.583 = 0.0084\text{W}$$

$$\text{Total Loss of the diode } (P_g) = 2.97\text{W}.$$

• DIODE HEAT SINK DESIGN:

Transient Thermal Impedance Junction-to-Case per diode at 1Khz (Z_{thjc}) = 2.2°C/W .

Transient Thermal Impedance coupling at 1Khz (Z_{thc}) = 0.3C/W .

$$\begin{aligned} \text{Junction Temperature rise with respect to case} &= P_g / 2 * (Z_{thjc} + Z_{thc}) \text{ (from datasheet)} \\ &= 3.71^\circ\text{C rise} \end{aligned}$$

Let maximum junction temperature T_j be 125°C .

$$\text{Then, maximum case temperature } T_c = 125 - 3.71 = 121.29^\circ\text{C}$$

Let the ambient temperature be 40°C .

$$\text{Maximum heat sink thermal Impedance (Case to ambient) } (Z_a) = \frac{T_c - T_a}{P_g} = \frac{121.29 - 40}{P_g} = 27.37^\circ \frac{\text{C}}{\text{W}}$$

$$\text{Heat sink thermal Impedance (Case to ambient) } (Z_a) = 16^\circ\text{C/W (ATS-PCB1008)}$$

$$\text{Case Temperature rise with respect to ambient} = P_g * Z_a = 2.97 * 21.2 = 47.52^\circ \text{ rise}.$$

$$\text{Junction Temperature } (T_j) = 40^\circ + 62.96^\circ + 3.71^\circ\text{C} = 91.23^\circ\text{C}.$$

Here junction temperature is well within the operating temperature range of the diode.

$$\text{Total semiconductor Loss} = 6.79\text{W} + 2.97\text{W} = 9.76\text{W}$$

5. DESIGN OF INDUCTOR:

For Boost converter, Inductor current = Input current.

Inductor ripple current has to be 30% at rated load.

Case 1:	Case 1:
$V_{in} = 28.8\text{V}$	$V_{in} = 20\text{V}$
$I_{in} = \frac{1}{(1-D)} I_o = 6.94\text{A}$	$I_{in} = \frac{1}{(1-D)} I_o = 10\text{A}$
$\Delta I_L = 0.3 * 6.94 = 2.08\text{A}$	$\Delta I_L = 0.3 * 10 = 3\text{A}$
$L = \frac{1}{\Delta I_L f_s} V_{in} D = 110.66\mu\text{H}$	$L = \frac{1}{\Delta I_L f_s} V_{in} D = 77.73\mu\text{H}$

Worst case Inductor Value $L = 110.66\mu\text{H}$

$$\text{For } I_L = 10\text{A. } \Delta I_L = \frac{20 \cdot 0.583}{500000 \cdot 110.66\mu} = 2.11\text{A}$$

$$I_{Lrms} = \sqrt{\frac{1}{T} \left(\int_0^{DT} \left(\frac{\Delta I_L}{DT} t + I_{Lmin} \right)^2 dt + \int_{DT}^T \left(-\frac{\Delta I_L}{(1-D)T} t + I_{Lmax} \right)^2 dt \right)}$$

$$I_{Lrms} = \sqrt{I_{Lmax}^2(1-D) + I_{Lmin}^2(D) + \frac{\Delta I_L^2}{3} + \Delta I_L(DI_{Lmin} - (1-D)I_{Lmax})}$$

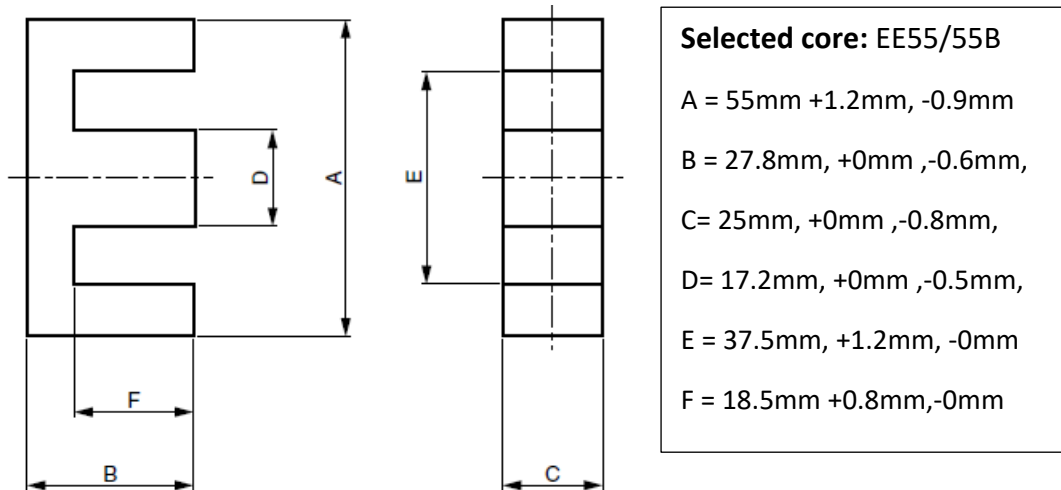
$$= \sqrt{10.725^2 \cdot 0.417 + 9.275^2(0.583) + \frac{1.45^2}{3} + 1.45(0.583 \cdot 9.275 - 0.417 \cdot 10.725)}$$

$$= 10.008\text{A}$$

Inductance(L)	110.66μH
Peak Current(I_p)	11.06A*1.1 = 12.17A(To account for losses)
Max. average current (I_{avg})	10A
B_m	0.2 wb/m ²
J(initial)	3A/mm ²
K_w (initial)	0.3

$$\text{Area Product, } A_c A_w = \frac{L \cdot I_p \cdot I_{avg}}{K_w \cdot B_m \cdot J} = 74818.46\text{mm}^4$$

Selected core: EE55/28/25 is selected.



$$\text{. Minimum } A_c = C * D = (25 - 0.8) * (17.2 - 0.5) = 404.14\text{mm}^2$$

$$A_w = (E - D) * F = (37.5 - 17.2) * 18.5 = 375.55\text{mm}^2,$$

$$\text{Number of turns: } N = \frac{L I_p}{B_m A_c} = 18.25 \approx 19$$

Wire Size: $a_w = \frac{I_{rms}}{J} = \frac{10.008}{3} = 3.34mm^2$

Chosen wire: SWG 21 *4* 2.

Updated wire size: $a_w^* = 0.5189 * 8 = 4.15mm^2$ (Even no is chosen due to manufacturing reason)

Thickness of the wire (t_c) = $0.874 * 4 * 1.05(5\% \text{ tolerance}) = 3.67mm$

Minimum Window width = $8.35mm$

Height of the winding = $0.874 * 2 * 19 * 1.1(10\% \text{ Tolerance}) = 36.53mm$ (10% for transposing conductors for all eight strands to have nearly equal length).

Minimum Window height = $18.5 * 2mm = 37mm$

Updated current density: $J^* = \frac{I_{rms}}{a_w^*} = 2.411A/mm^2$

Updated area product: $A_c A_w = 151774mm^4$

Air gap length: $l_g = \frac{N^2 A_c \mu_0}{L} = 1.66mm \ll \sqrt{A_c}$ (To avoid fringing effect)

Average length of each turn of a conductor = $2 * (C + D + t_c) = 91.74mm$

Average length of inductor coil: $N * t_c = 1.743m$

Coil resistance of inductor: $\frac{33.23 * 1.743}{1000 * 8} = 7.24m\Omega$

Updated inductance (L) = $\frac{NB_m A_c}{I_p} = 115.18\mu H$

Conduction Loss in Inductor = $I_{Lrms}^2 * r_l = 0.725W$.

6. DESIGN OF OUTPUT CAPACITOR:

Capacitor voltage ripple has to be 2% at rated load.

Capacitor Ripple Voltage $\Delta V_{C(p-p)} = \frac{V_{out} * D_{max} * Ts}{R_{Lmin} * C}$

Value of Capacitance C = $\frac{V_{out} * D * Ts}{R_{Lmin} * \Delta V_{C(p-p)}} = \frac{48 * 0.583}{50000 * 11.52 * 0.96} = 50.6\mu F \approx 47$

Rms current of the capacitor $I_{crms} = \sqrt{\frac{1}{T} \left(\int_0^{DT} I_o^2 dt + \int_{DT}^T \left(-\frac{\Delta I_L}{(1-D)T} t + I_{Lmax} \right)^2 dt \right)}$

$$= \sqrt{I_o^2 D + I_{Lmax}^2 (1-D) + \frac{\Delta I_L^2}{3} (1-D) - \Delta I_L (1-D) I_{Lmax}}$$

$$= \sqrt{4.167^2 * 0.583 + 10.725^2 (0.417) + \frac{1.45^2}{3} (0.417) - 1.45 * 0.417 * 10.725}$$

$$= 7.203A$$

Capacitor Chosen is 3 electrolytic capacitor type : (3x 100V 18 μ F 100SXE18M) capacitors in parallel, with a ripple current rating of 3A and ESR of 30m Ω each.

Electrolytic capacitors is not chosen because of their low ripple current rating

$$\text{Power loss in capacitor} = I_{rms}^2 * ESR = 7.203^2 * \frac{30}{3} m\Omega = 0.52W$$

7. TOTAL LOSS AND EFFICIENCY CALCULATION AT RATED LOAD:

$$\text{Total Power Loss} = 9.76W + 0.725W + 0.52 = 10.635W$$

$$\text{Full load efficiency of Boost converter} = \frac{\text{Output Power}}{\text{Output Power} + \text{Losses}} * 100\% = \frac{200}{211.005} * 100 = 94.78\%$$

REFERENCES

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2. “*Calculation of reverse losses in a power diode, AN4021*” Application Note by ST Microelectronics.
3. V. Ramanarayanan, “Course Material on Switched Mode Power Conversion”, Department of Electrical Engineering Indian Institute of Science Bangalore 560012, second edition 2006.